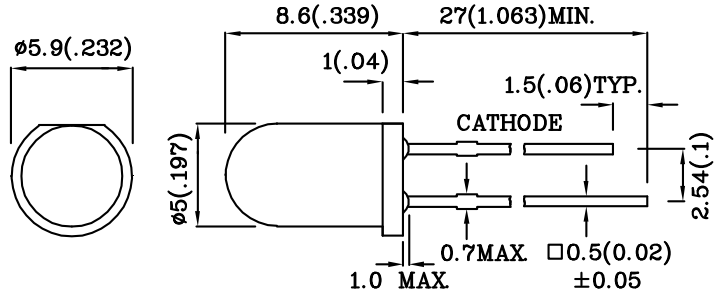


**Features**

- LOW POWER CONSUMPTION.
- POPULAR T-1 3/4 DIAMETER PACKAGE.
- GENERAL PURPOSE LEADS.
- RELIABLE AND RUGGED.
- LONG LIFE - SOLID STATE RELIABILITY.
- AVAILABLE ON TAPE AND REEL.
- 14V INTERNAL RESISTOR.
- RoHS COMPLIANT.



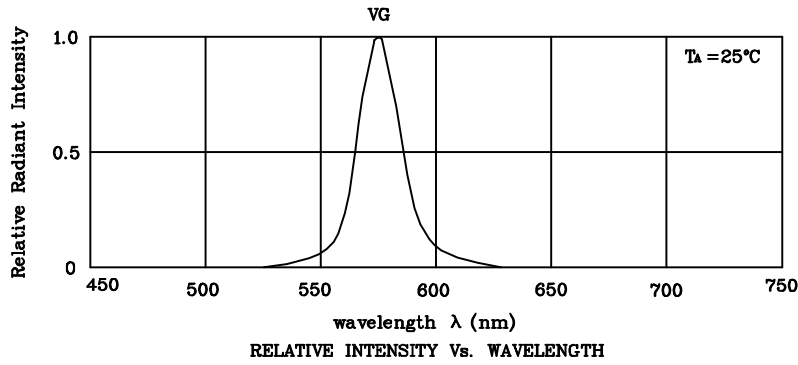
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.

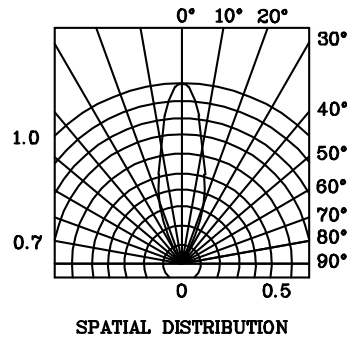
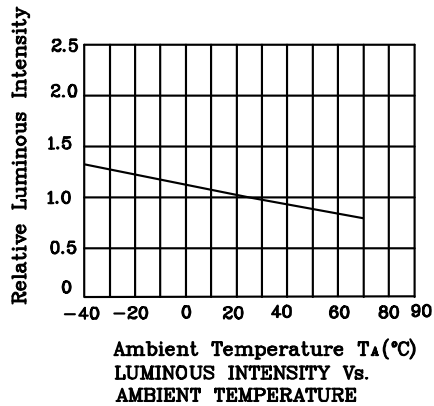
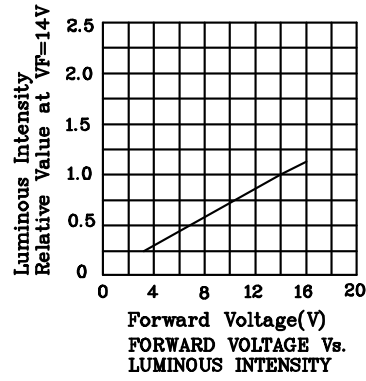
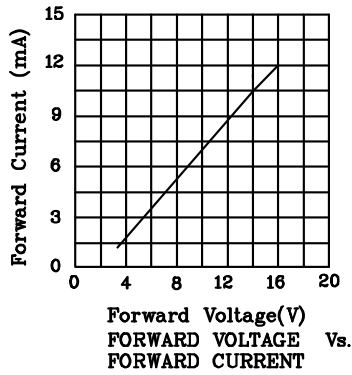
Absolute maximum ratings ( $T_A=25^\circ\text{C}$ )		VG (InGaAlP)	Unit
Reverse Voltage	$V_R$	5	V
Forward Voltage	$V_F$	16	V
Power Dissipation	$P_T$	160	mW
Operating Temperature	$T_A$	-40 ~ +70	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	
Lead Solder Temperature [2mm below package base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm below package base]	260°C For 5 Seconds		

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		VG (InGaAlP)	Unit
Forward Current (typ.) ( $V_F=14\text{V}$ )	$I_{F \text{ typ}}$	10.5	mA
Forward Current (max.) ( $V_F=14\text{V}$ )	$I_{F \text{ max}}$	13.5	mA
Reverse Current ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission ( $V_F=14\text{V}$ )	$\lambda_{\text{ peak}}$	574	nm
Wavelength of Dominant Emission ( $V_F=14\text{V}$ )	$\lambda_D$	570	nm
Spectral Line Full Width At Half-Maximum ( $V_F=14\text{V}$ )	$\Delta\lambda$	20	nm

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ( $V=14\text{V}$ ) mcd		Wavelength nm $\lambda_P$	Viewing Angle $2\theta_{1/2}$
				min.	typ.		
XLVG12D14V	Green	InGaAlP	Green Diffused	8	49	574	30°



❖ VG



Remarks:

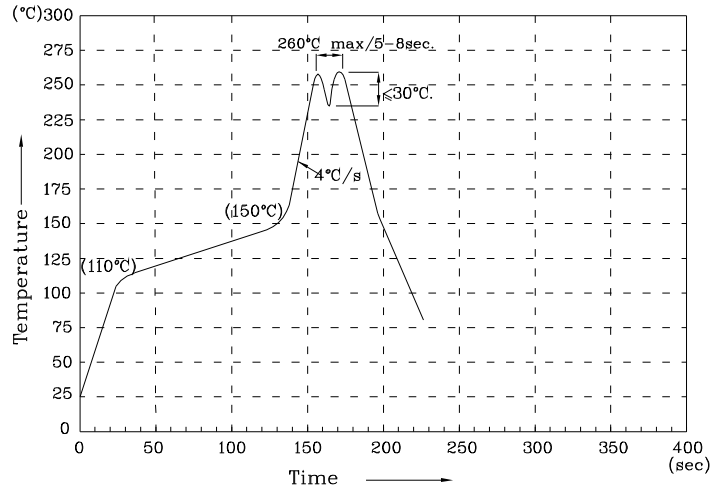
If special sorting is required (e.g. binning based on luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%

Note: Accuracy may depend on the sorting parameters.

XLVG12D14V

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.